



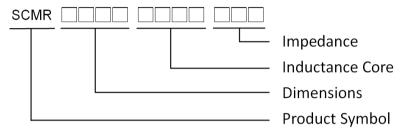
#### .Features:

- 1. High impedance at high frequency effects excellent noise suppression performance.
- 2. The choke coils structure enables noise suppression without degrading the signal.

#### .Applications:

The SCMR Series is SMD common mode filter specifically designed to eliminate common mode noise in USB 2.0, IEEE1394, and LVDS applications.

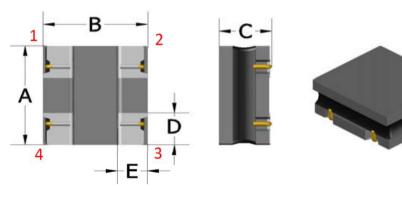
#### .Product Identification :



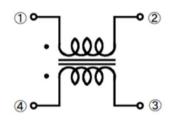
#### .Rating

- 1.Operating temperature : 25°C ~ + 85°C
- 2.Storage conditions: 40°C to + 85°C, 70%RH max

#### Shape and Dimensions

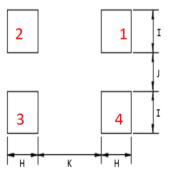


#### Schematic



#### Dimensions in mm

Part No.	Α	В	С	D	E
SCMR5045P2S	5	4.5	2.5	1.6	1.4
	±0.3	±0.3	Max.	±0.3	±0.3



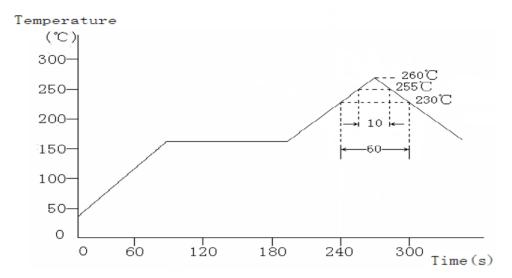
#### Dimensions in mm

Part No.	Н	I	J	K
SCMR5045P2S	1.38	1.58	2.35	1.85
3CIVIN3043F23	Тур.	Тур.	Тур.	Тур.





## .Reflow Soldering Heat Endurance

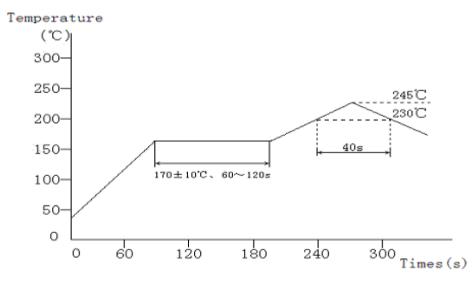


No mechanical and electrical defects are found after testing based on the above profile and keeping under the conditions of room temperature and humidity for 2 hours.

Twice reflow test is acceptable with the test interval remaining 1 hour under the normal conditions.

The reflow test profile may vary with the testing instruments.

### .Recommended Reflow Conditions.



The recommended reflow profile is based on the testing instruments used. Solder ability will reflow conditions, testing method, etc. So it is necessary to make a confirmation of them when the reflow conditions are set up.





## . Electrical Characteristics (SCMR5045P2S TYPE)

Part No.	Impedance	DCR	Rated Current	Withstand Volt.	Rated Volt.	I.R
Fait No.	(Ω) Typ. 100MHz	$(\Omega) \pm 40\%$	(A) Max.	(V) Typ.	(V) Typ.	(mΩ) Min.
SCMR5045P2S-101	100	0.009	6.0	125	50	10
SCMR5045P2S-251	250	0.014	5.0	125	50	10
SCMR5045P2S-351	350	0.014	4.5	125	50	10
SCMR5045P2S-501	500	0.019	4.0	125	50	10
SCMR5045P2S-102	1000	0.024	3.0	125	50	10
SCMR5045P2S-142	14000	0.040	1.5	125	50	10

#### NOTE

- 1. IDC:The actual value of D.C. current when the temperature rise is  $\triangle t = 40^{\circ}$  (Ta=20°C).
- 2. Test Instrument: Impedance(Agilent 4291B) . DCR(Chroma 16502) . I.R(4339B).
- 3. If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting.





# ☑. Reliability and Test Conditions(可靠性測試條件) Mechanical Performance

ITEM	Performance	Test Condition
Appearance and Dimensions	Visual Inspection and measured with Side Calipers.	
Bonding Strength and Core Strength	Applying Force (F):10N Applying Time 5±1s  Pressure jig  Substrate  Test board fixture	No evidence of chipping. Breakage No evidence of coming off glass- epoxy substrate.
Body strength	Applying Force (F):10N Applying Time 5±1s  Test board fixture  Product Substrate	No evidence of chipping. Breakage
Bending strength	Substrate: Glass-epoxy(t=1.6mm) Deflection: 2.0mm Keeping Time: 30 s Speed of Applying Force: 0.5mm/s  Pressure jig  Pressure jig  Pressure jig  Pressure jig  R340  Pressure jig  R340  Pressure jig  R340  Pressure jig	Meet Table 1. Table 1  Appearance No damaged. Impedance change within ± 20% (at 10MHz) I.R. 10MΩ min. Withstanding Voltage No damaged.
Vibration	Products shall be soldered on the substrate. Oscillation Frequency: 10 to 55 to 10Hz for 1 min. Total Amplitude: 1.5mm Testing Time: A period of 2 hours in each of 3 mutually perpendicular directions(Total 6 hours).	
Drop	Products shall be dropped concrete or steel board.  Method : free fall  Height : 1m  The Number of Times: 10 Times	





ITEM	Performance	Test Condition
Solderability	Flux : Ethanol solution of rosin, 25(wt)%  Pre heating : 150±10°C (2) 245±5°C  Immersion Time : 4±1s  Immersion and Immersion rates : 25mm/s  Stainless tweezers  Product	The electrodes shall be at least 90% covered with new solder coating.
Resistance to Soldering heat	Flux: Ethanol solution of rosin, 25(wt)% Pre heating: $150\pm10^{\circ}$ C (2) $245\pm5^{\circ}$ C Solder: Sn/Pb = $60/40$ or Sn-3.0 Ag-0.5Cu Solder Temperature: $270\pm5^{\circ}$ C Immersion Time: $5\pm1s$ Immersion and Immersion rates: $25$ mm/s Then measured after exposure in the room condition for 4 to 48 hours.	Meet Table 1.

# **Enviromental Performance** (Product shall be solderd on the glass-epoxy substrate (t=1.6mm)

ITEM	Performance	Test Condition
Temperature Cycle	1 Cycle 1 step: -25°C (+0,-3)°C / 30min(+3,-0) min 2 step: Ordinary temp. /3 min max. 3 step: +85°C (+3,-0)°C / 30min(+3,-0) min 4 step: Ordinary temp. /3 min max. Total of 10 cycles Then measured after exposure in the room condition for 4 to 48 hours.	Meet Table 1.
Humidity	Temperature: 40±2°C Humidity: 90 to 95%(RH) Time: 1000 h (+48h, -0h) Then measured after exposure in the room condition for 4 to 48 hours. (ref. item)	
Humidity Load	Temperature: 40±2°C Humidity: 90 to 95%(RH) Test Voltage: Rated Voltage Time: 1000 h (+48h, -0h) Then measured after exposure in the room condition for 4 to 48 hours. (ref. item)	
Heat life	Temperature: 85±2°C Test Voltage: 2 Times for Rated Voltage Time: 1000 h (+48h, -0h) Then measured after exposure in the room condition for 4 to 48 hours. (ref. item)	
Cold Resistance	Temperature: -40±2°C Time: 1000 h (+48h, -0h) Then measured after exposure in the room condition for 4 to 48 hours. (ref. item)	





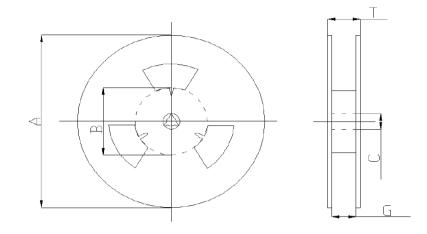
# Terminal to be Tested

ITEM	ITEM	Terminal to be Tested
1	Impedance (   Z   ) (Measurement Termianl)	Terminal → ← ← Terminal
2	DC Resistance (RDC) (Measurement Termianl)	
3	Insulation Resistance (I.R.) (Measurement Termianl)	
4	Withstanding Voltage (Measurement Termianl)	Terminal •
5	Humidity Load (Supply Terminal)	<i>→</i> • <u> </u>
6	Heat Life (Supply Terminal)	



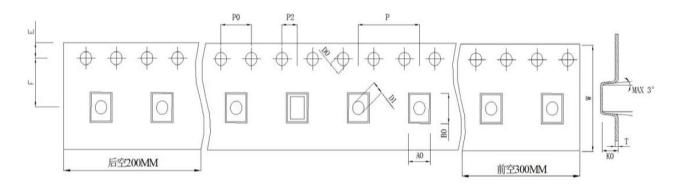


# .Reel Dimension(m/m)



Item	Α	В	С	D	E
13"x12	300	100	13	12.5	16.4

# .Taping Dimension(m/m)



Item	W	A0	В0	K0	Е	F	Р	P0
12mm	12	5.1	4.9	2.7	1.75	5.5	8	4
12/11/11	± 0.3	± 0.1	± 0.1	± 0.1	± 0.1	± 0.1	± 0.1	± 0.1

P2	D0	D1	T
2	1.5	1.5	0.35
± 0.1	± 0.1	± 0.3	Ref.

Packing Unit	Carton Packing Unit
2,500 PCS / REEL	15,000 PCS / Box